



GDZ2V7LP3 - GDZ24LP3

ULTRA-SMALL LEADLESS SURFACE MOUNT ZENER DIODE

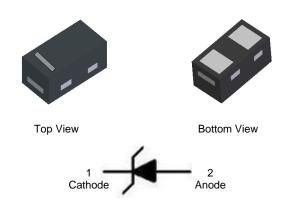
Features

- Ultra-Small Leadless Surface Mount Package (0.6 x 0.3mm)
- Ultra-Low Profile Package (0.3mm)
- Ideally Suited for Automated Assembly Processes
- Low Leakage Current, Suitable for Battery-Powered Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish Matte Tin over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.2 mg (Approximate)

X3-DFN0603-2



Ordering Information (Note 4)

Part Number	Case	Packaging
(Type Number)-7*	X3-DFN0603-2	10,000/Tape & Reel

^{*}Add "-7" to the appropriate type number in Electrical Characteristics Table. Example: 6.2V Zener = GDZ6V2LP3-7.

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Pin 1

xx = Product Type Marking Code (See Electrical Characteristics Table) Line Denotes Cathode Side



Thermal Characteristics

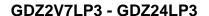
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) T _A = +25°C	P _D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5) T _A = +25°C	R _{0JA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

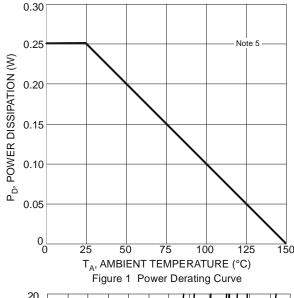
Type Marking Number Code		Zener Voltage Range (Note 6)		Reverse Current (Note 6)				
Number	Code	Vz @ Izτ Izτ		I _R		@ V _R		
		Nom (V)	Min (V)	Max (V)	mA	Typical (µA)	Max (µA)	V
GDZ2V7LP3	JB	2.7	2.57	2.84	5	-	20	1.0
GDZ3V0LP3	JC	3.0	2.85	3.15	5	-	10	1.0
GDZ3V3LP3	JD	3.3	3.14	3.47	5	-	10	1.0
GDZ3V6LP3	KU	3.6	3.41	3.79	5	-	10	1.0
GDZ3V9LP3	KJ	3.9	3.740	4.160	5	-	5	1.0
GDZ4V1LP3	KY	4.1	3.93	4.37	5	-	5.0	1.0
GDZ4V3LP3	KK	4.3	4.08	4.53	5	-	5.0	1.0
GDZ4V7LP3	KL	4.7	4.420	4.900	5	-	2.0	1.0
GDZ5V1LP3	KM	5.1	4.840	5.370	5	-	0.2	2.0
GDZ5V6LP3	KN	5.6	5.310	5.920	5	- 90	1.0 175	2.5 4.75
GDZ6V0LP3	KW	6.0	5.676	6.324	5	-	1.0	2.8
GDZ6V2LP3	КО	6.2	5.860	6.530	5	-	1.0	3.0
GDZ6V8LP3	KT	6.8	6.470	7.140	5	-	0.5	3.5
GDZ7V5LP3	KQ	7.5	7.060	7.840	5	-	0.5	4.0
GDZ8V2LP3	KX	8.2	7.760	8.640	5	-	0.5	5.0
GDZ9V1LP3	JE	9.1	8.65	9.56	5	-	0.5	6.0
GDZ10LP3	JF	10	9.50	10.50	5	-	0.2	7.0
GDZ11LP3	JG	11	10.45	11.55	5	-	0.1	8.0
GDZ12LP3	JH	12	11.40	12.60	5	-	0.1	8.0
GDZ13LP3	JI	13	12.35	13.65	5	-	0.1	8.0
GDZ15LP3	JJ	15	14.25	15.75	5	-	0.1	10.5
GDZ16LP3	JK	16	15.20	16.80	5	-	0.1	11.2
GDZ18LP3	JL	18	17.10	18.90	5	-	0.1	12.6
GDZ20LP3	JM	20	19.00	21.00	5	-	0.1	14.0
GDZ22LP3	JN	22	20.90	23.10	5	-	0.1	15.4
GDZ24LP3	JO	24	22.80	25.20	5	-	0.1	16.8

5. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can Notes: be found on our website at http://www.diodes.com.

6. Short duration pulse test used to minimize self-heating effect.







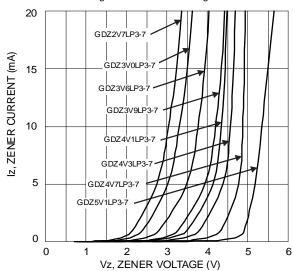
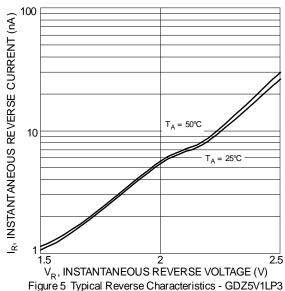
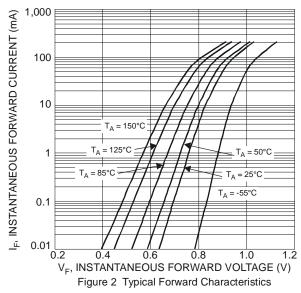


Figure 3 Typical Zener Breakdown Characteristics, GDZ2V7LP3 – GDZ5V1LP3





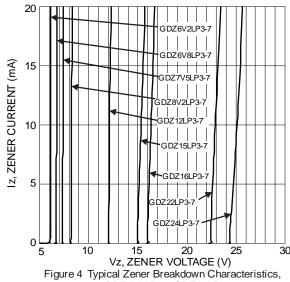


Figure 4 Typical Zener Breakdown Characteristics, GDZ6V2LP3 – GDZ24LP3

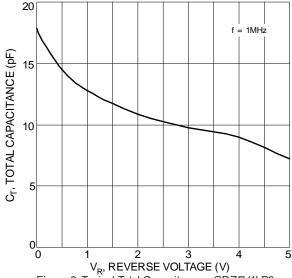
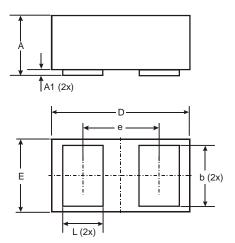


Figure 6 Typical Total Capacitance – GDZ5V1LP3



Package Outline Dimensions

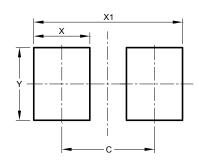
Please see http://www.diodes.com/package-outlines.html for the latest version.



X3-DFN0603-2				
Dim	Min	Max	Тур	
Α	0.27	0.35	0.30	
A1	0.00	0.03	0.02	
b	0.19	0.29	0.24	
D	0.595	0.645	0.62	
Е	0.295	0.345	0.32	
е	-	-	0.355	
L	0.14	0.24	0.19	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value	
Dillielisions	(in mm)	
С	0.380	
Х	0.230	
X1	0.610	
Y	0.300	



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2017, Diodes Incorporated

www.diodes.com